



SOT762-1

plastic, dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; 0.5 mm pitch; 2.5 mm x 3 mm x 0.85 mm body

2 August 2019

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	DHVQFN14
Package type industry code	DHVQFN14
Package style descriptive code	DHVQFN (DIL-compatible thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
JEDEC package outline code	MO-241
Mounting method type	S (surface mount)
Issue date	05-05-2015
Manufacturer package code	SOT762

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	2.9	3	3.1	mm
package width	2.4	2.5	2.6	mm
seated height	-	-	1	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	14	-	

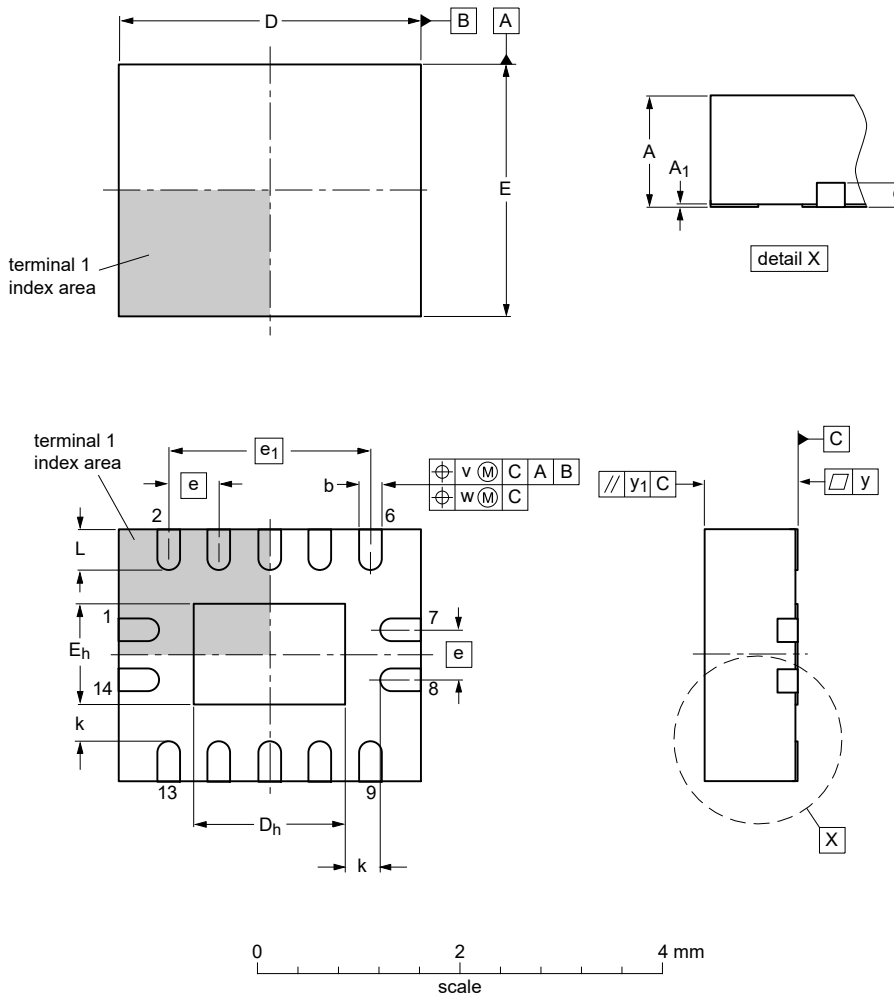


plastic, dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; 0.5 mm pitch; 2.5 mm x 3 mm x 0.85 mm body

2 Package outline

DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 3 x 0.85 mm

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Dimensions (mm are the original dimensions)

Unit	A ⁽¹⁾	A ₁	b	c	D ⁽¹⁾	D _h	E ⁽¹⁾	E _h	e	e ₁	k	L	v	w	y	y ₁
max	1	0.05	0.30		3.1	1.65	2.6	1.15				0.5				
mm nom		0.02	0.25	0.2	3.0	1.50	2.5	1.00	0.5	2		0.4	0.1	0.05	0.05	0.1
min		0.00	0.18		2.9	1.35	2.4	0.85			0.2	0.3				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sot762-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT762-1		MO-241			15-04-10 15-05-05

Figure 1. Package outline DHVQFN14 (SOT762-1)

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3 Soldering

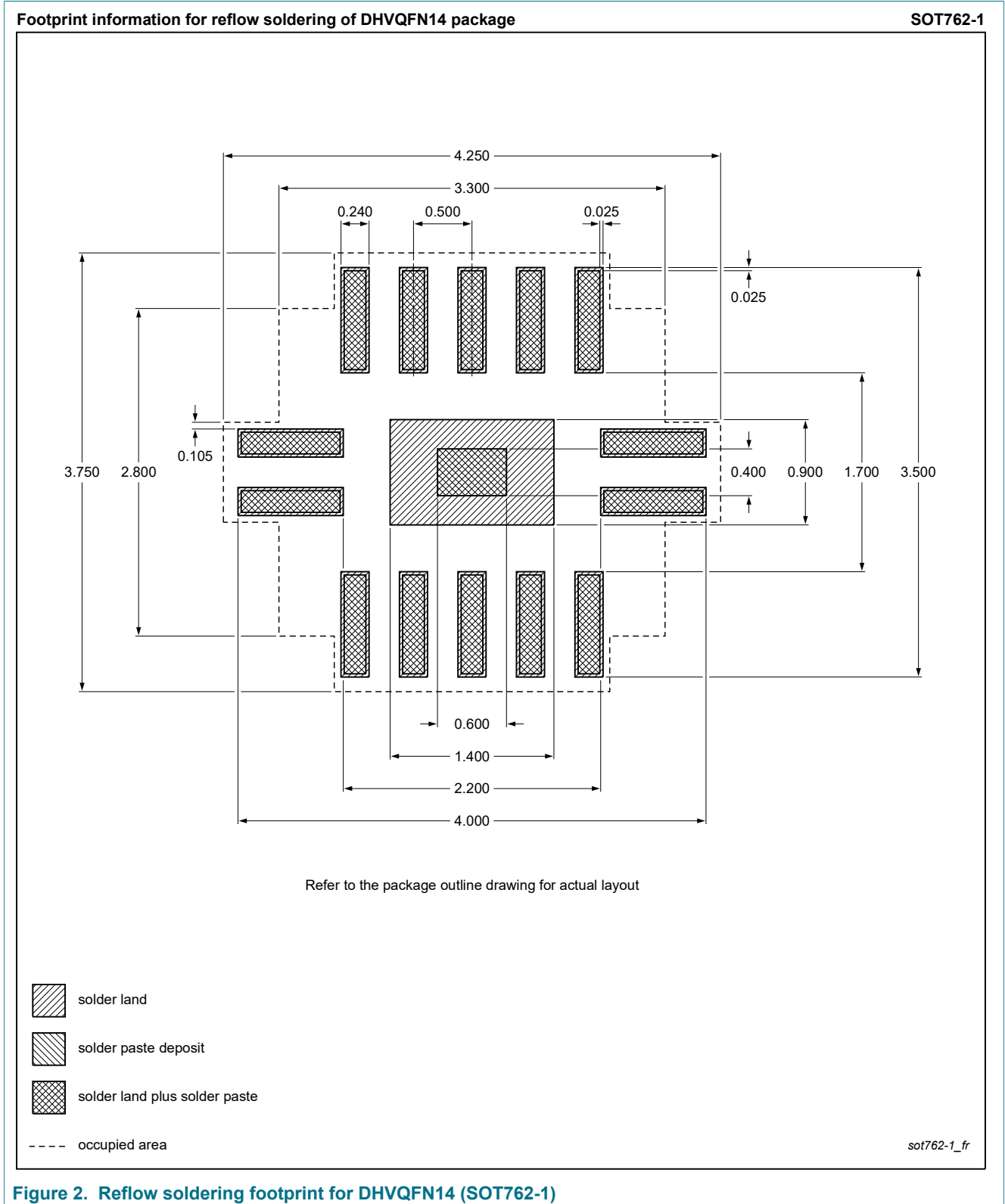


Figure 2. Reflow soldering footprint for DHVQFN14 (SOT762-1)

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4 Legal information

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